Docket No.: 09450/100K673-US2 (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Masahiko FURUNO et al.

Application No.: 10/771,990 Confirmation No.: 3571

Filed: February 3, 2004

Art Unit: 1725

Examiner: Michael Aboagve

For: BUMP FORMING METHOD,

PRESOLDERING TREATMENT METHOD, SOLDERING METHOD, BUMP FORMING APPARATUS, PRESOLDERING TREATMENT DEVICE AND SOLDERING

APPARATUS

RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the non-final Office Action dated August 8, 2007, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 10 of this paper.